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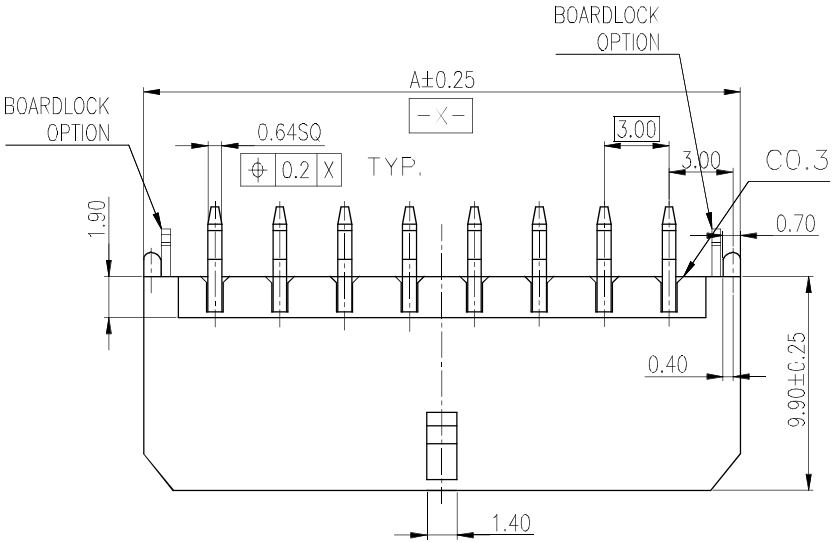
The marking on thisproduct doesn't contain environmental hazardous materials per Material Specification SS-00259 for Sony GP compliant or per directive 2011/65/EC for RoHS compliant.

Amphenol Taiwan RoHS Compliant 2011/65/EU

ORIGINAL

ISSUED BY AMPHENOL TAIWAN PDF Format D.C.

REVISIONS				
SYM	ECN No.	DESCRIPTION	DATE	APPROVED
A		RELEASE FOR RoHS	07/04/2006	Armstrong Koo
B	NE-06295	MODIFIED DRAWING	09/06/2006	Edward Wu
C	NE-09209	MODIFIED DRAWING	12/30/2009	Arron Lin
D	NE-10003	MODIFIED DRAWING	01/07/2010	Arron Lin
E	NE-10028	ADD LOCK KEY DIMENSION	03/04/2010	Roger Tsai
F	NE-11043	MODIFIED DRAWONG	03/28/2010	Arron Lin
A1	NE-11069	ADD PLATING OPTIONS AND POS P/N INTO DRAWING	06/07/2011	Arron Lin
B1	NE-11120	MODIFY THE DESCRIPTION	09/02/2011	Arron Lin
C1	NE-12012	ADDED POST DIM. 0.95	01/31/2012	Arron Lin
D1	NE-12023	DIMENSION 1.98 CHANGED TO 2.05mm	02/21/2012	Arron Lin
E1	NE-12113	REMOVE 2 POS OPTIONS AND UPDATE PACKING QUANTITY.	07/04/2012	Arron Lin
F1	NE-13034	MODIFY PLATING TO OVERALL	03/13/2013	Arron Lin
A2	NE-13197	ADDED DIM & UPDATE FINISH NOTE	12/06/2013	Arron Lin
B2	NE-15054	ADD 2PIN AND UPDATE PACKING	04/29/2015	Roger Tsai
C2	NE-15114	ADD BOARDLOCK OPTION	09/15/2015	Roger Tsai

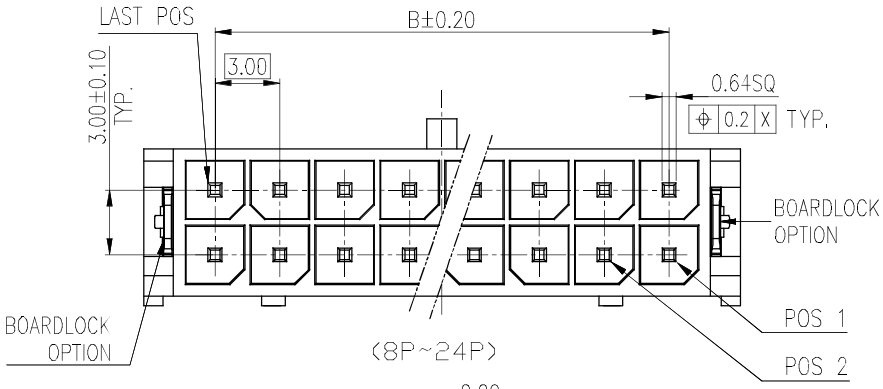


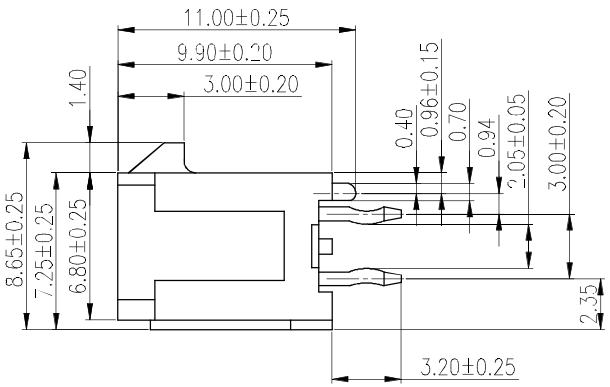
PART NO. G881AXX1XXTEU

- No. OF CIRCUIT
- CONTACT FINISH
  - 0: Tin (OVERALL)
  - 1: FLASH GOLD (OVERALL)
  - 2: 15 u" GOLD
  - 3: 30 u" GOLD
- BOARDLOCK
  - 1: W/BOARDLOCK
  - 2: W/O BOARDLOCK

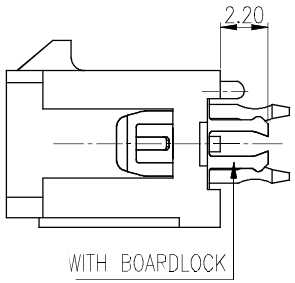
NOTE:

1. INSULATOR: HIGH TEMP. THERMOPLASTIC, LCP, UL 94V-0, COLOR: BLACK.
2. CONTACT MATERIAL:COPPER ALLOY;
3. FINISH:
   CONTACT: SELECTIVE PLATING. ;
   SOLDERING AREA: MATTE TIN 100u" MIN. OR GOLD PLATING;
   UNDER PLATING: NICKEL PLATING 50 μ" THICKNESS MIN. OVERALL.
4. THIS PRODUCT DOESN'T ENVIRONMENTAL HAZARDOUS MATERIALS PER DIRECTIVE 2011/65/EC FOR RoHS.
5. PACKING MUST BE PER Amphenol PACKING SPECIFICATION





WITHOUT BOARDLOCK



WITH BOARDLOCK

24	39.60	33.00	39.00	37.3
22	36.60	30.00	36.00	34.3
20	33.60	27.00	33.00	31.3
18	30.60	24.00	30.00	28.3
16	27.60	21.00	27.00	25.3
14	24.60	18.00	24.00	22.3
12	21.60	15.00	21.00	19.3
10	18.60	12.00	18.00	16.3
08	15.60	9.00	15.00	13.3
06	12.60	6.00	12.00	10.3
04	9.60	3.00	9.00	7.3
02	6.60		6.00	4.3
NO. OF CIRCUIT	A	B	C	D

TOLERANCE	APPROVALS	DATE
X.	DRAWN Aqua Chou	09/15/2015
X.X ±0.30	CHECKED Roger Tsai	09/15/2015
X.XX ±0.20	APPROVED Roger Tsai	09/15/2015
X.XXX ±0.10	DWG TYPE CUST DWG	PROJECT CODE PHD
ANGULAR ±1°		
UNLESS OTHERWISE SPECIFIED		

TITLE: G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT PCB MOUNT

Amphenol®
Amphenol Corporation
Amphenol Taiwan Corporation

UNIT	SIZE	PART No.	REV.
mm	A3	G881AXX1XXTEU	
SCALE NA	SHEET 1 OF 3	DWG No. G881AXX1XXTEU	C2

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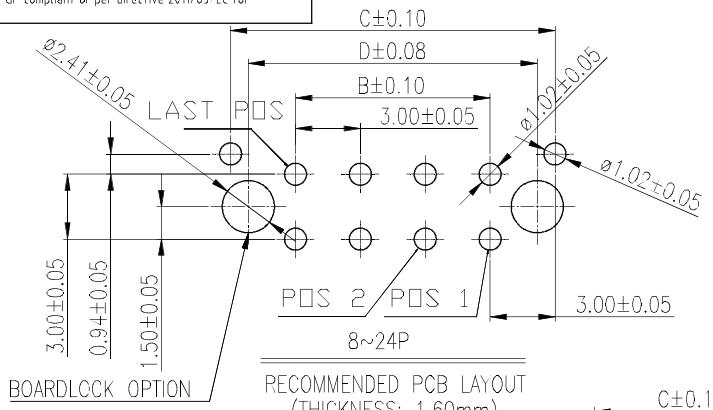
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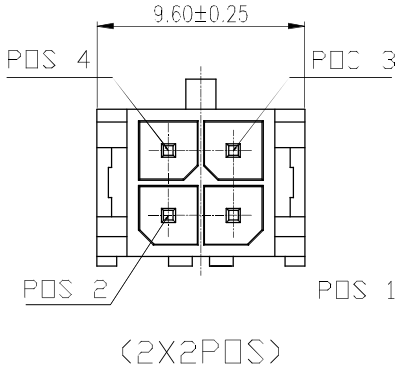
ORIGINAL

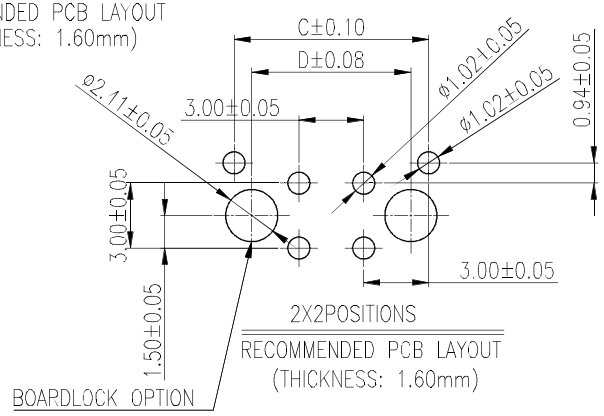
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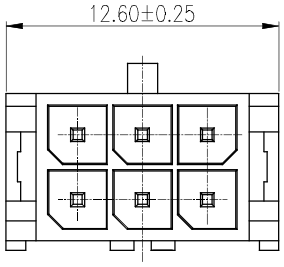
Amphenol Taiwan RoHS Compliant 2011/65/EU

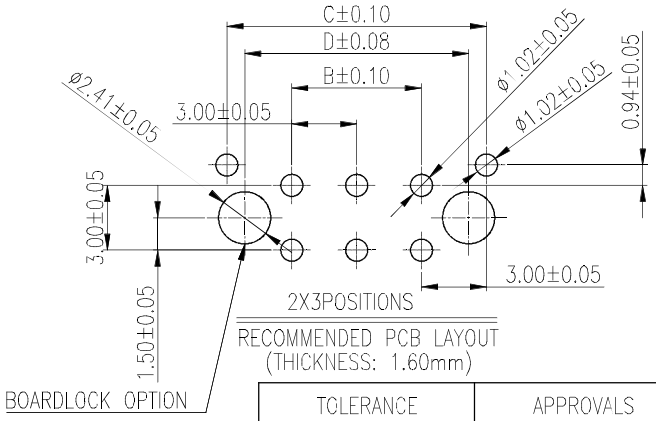
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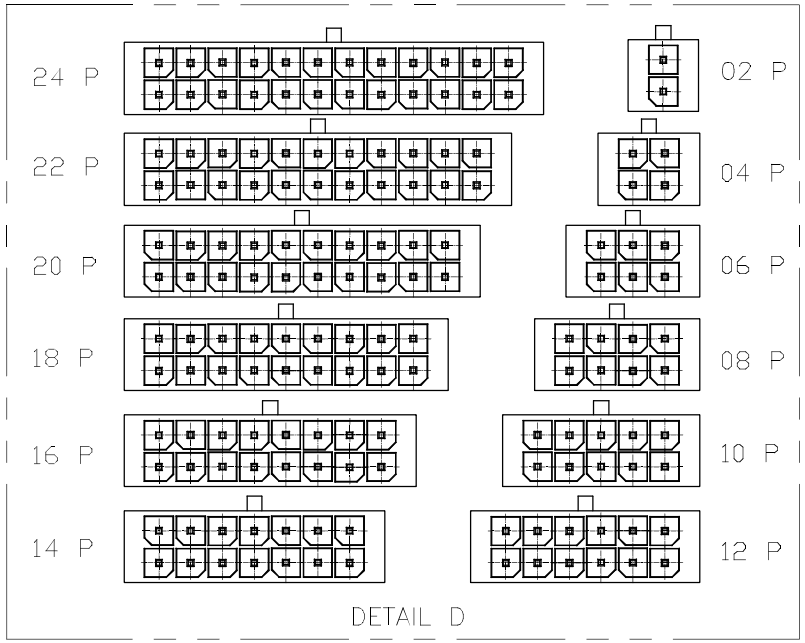












TOLERANCE	APPROVALS	DATE
X.	DRAWN Aqua Chou	09/15/2015
X.X ±0.30	CHECKED Roger Tsai	09/15/2015
X.XX ±0.20	APPROVED Roger Tsai	09/15/2015
X.XXX ±0.10	DWG TYPE CUST DWG	PROJECT CODE PHD
ANGULAR ±1°		
UNLESS OTHERWISE SPECIFIED		

TITLE: G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT PCB MOUNT

Amphenol®
Amphenol Corporation
Amphenol Taiwan Corporation

UNIT	SIZE	PART No.	REV.
mm	A3	G881AXX1XXTEU	
SCALE NA	SHEET 2 OF 3	DWG No. G881AXX1XXTEU	C2

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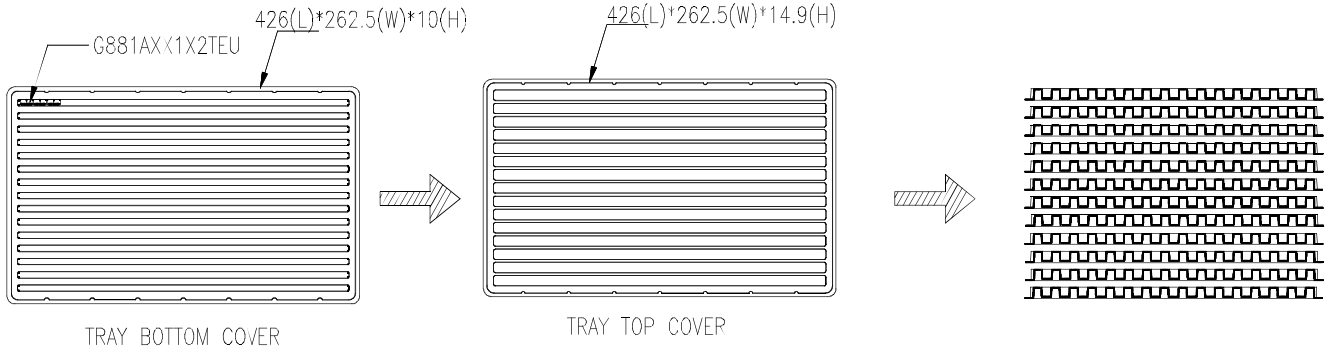
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Amphenol Taiwan RoHS Compliant 2011/65/EU

ORIGINAL

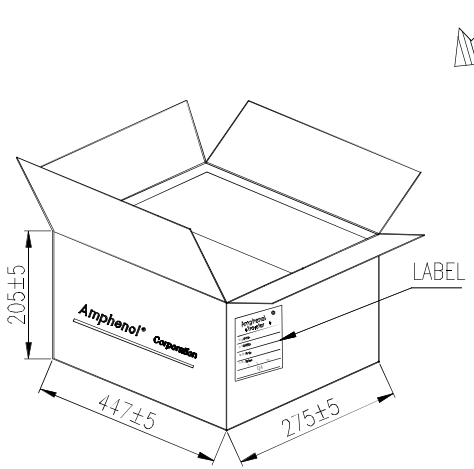
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TRAY BOTTOM COVER

TRAY TOP COVER



(12 INSIDE CARTON)

POS	PCS/TRAY	PCS/CARTON
02	900	10800
04	615	7380
06	465	5580
08	375	4500
10	315	3780
12	270	3240
14	240	2880
16	210	2520
18	180	2160
20	165	1980
22	150	1800
24	150	1800

NOTE:
1. MATERIAL : TRANSPARENT CONDUCTIVE POLYSTYRENE ALLOY
2. ALL DIMENSIONS MEET EIA-481-C REQUIREMENTS.
3. THICKNESS : 0.80±0.05mm.

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UNLESS OTHERWISE SPECIFIED		

TITLE: G881A SERIES MICRO POWER, WAFER 3.00 MM PITCH STRAIGHT PCB MOUNT

UNIT mm | SIZE A3 | SCALE NA | SHEET 3 OF 3

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PART No. G881AXX1XXTEU

DWG No. G881AXX1XXTEU | REV. C2